

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc4368cms-1#trpbf

(Engineering Calculation)

MSOP

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**TOTAL MASS (g) : 0.027401**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002079	1000000	75873.0703125		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.010433	975000	380752.15625		
		Iron (Fe)	7439-89-6	0.000257	24000	9379.2109375		
		Phosphorus (P)	7723-14-0	0.000003	300	109.484947205		
		Zinc (Zn)	7440-66-6	0.000007	700	255.464889526		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.010700</b>	<b>1000000</b>	<b>390496.34375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000710	1000000	25912.3496094		
		<b>External Plating Total:</b>				<b>0.000710</b>	<b>1000000</b>	<b>25912.3496094</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000086	1000000	3138.56860352		
		<b>Internal Plating Total:</b>				<b>0.000086</b>	<b>1000000</b>	<b>3138.56860352</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000715	750000	26093.9121094		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000238	250000	8685.80566406		
<b>Die Attach Total:</b>				<b>0.000953</b>	<b>1000000</b>	<b>34779.71875</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001659	130000	60545.1757812		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.010591	830000	386518.375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000447	35000	16313.2568359		
		Carbon Black (C)	1333-86-4	0.000064	5000	2335.67895508		
		<b>Encapsulation Total:</b>				<b>0.012761</b>	<b>1000000</b>	<b>465712.46875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000112	1000000	4087.43823242		
					<b>TOTAL MASS (g) :</b>	<b>0.027401</b>		